



Material Content Data Sheet



Sales Product Name		BTS716GB		Issued		19. January 2018		
MA#		MA001365250						
Package		PG-DSO-20-32		Weight*		477.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.009	1.47	1.47	14667	14667
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75	
	non noble metal	zinc	7440-66-6	0.143	0.03		299	
	non noble metal	iron	7439-89-6	2.862	0.60		5988	
wire	non noble metal	copper	7440-50-8	116.197	24.31	24.95	243147	249509
	non noble metal	aluminium	7429-90-5	0.420	0.09	0.09	879	879
	encapsulation	organic material	carbon black	1333-86-4	0.692	0.14		1448
encapsulation	plastics	epoxy resin	-	31.836	6.66		66619	
	inorganic material	silicondioxide	60676-86-0	313.517	65.62	72.42	656049	724116
leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5746	5746
plating	noble metal	silver	7440-22-4	0.392	0.08	0.08	821	821
glue	plastics	epoxy resin	-	0.356	0.07		746	
	noble metal	silver	7440-22-4	1.680	0.35	0.42	3516	4262
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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